

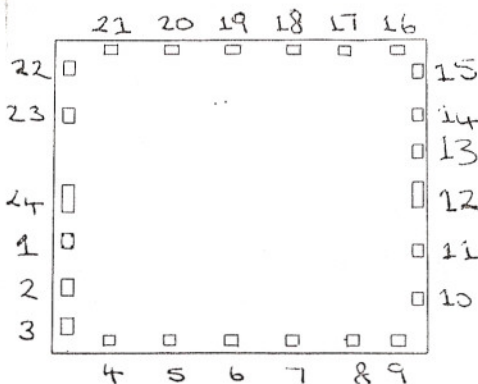


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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



NOTE: To aid orientation Pad 1 shows corner cut-outs.

Pad	Function	Pad	Function	Pad	Function
1	D ₇	9	CLK 0	17	OUT 2
2	D ₆	10	OUT 0	18	CLK 2
3	D ₅	11	GATE 0	19	A ₀
4	D ₄	12	GND	20	A ₁
5	D ₃	13	OUT 1	21	CS
6	D ₂	14	GATE 1	22	RD
7	D ₁	15	CLK 1	23	WR
8	D ₀	16	GATE 2	24	VCC

Topside Metal: Al

Backside: Si

Backside Potential:

Mask Ref: 50187

Bond Pads: .004" min

APPROVED BY:CB

MFG: HARRIS

DIE SIZE: .154" x .128"

THICKNESS: .019"

DATE: 1/26/01

P/N: HDO-82C54-2